

SOT748-2

plastic chip on foil package; 35 mm wide tape

8 February 2016

Package information

1. Package summary

Terminal position code	S (single)
Package type descriptive code	COF
Package type industry code	COF
Package style descriptive code	COF (chip on foil)
Package style suffix code	NA (not applicable)
Package body material type	P (plastic)
Mounting method type	S (surface mount)
Issue date	18-10-2002

Table 1. Package summary

Symbol	Parameter		Min	Typ	Nom	Max	Unit
D	package length		34.8	-	35	35.2	mm
A	seated height		[tbd]	-	1	1	mm
A ₂	package height		[tbd]	-	1	1	mm
n ₂	actual quantity of termination		-	-	0	-	



2. Package outline

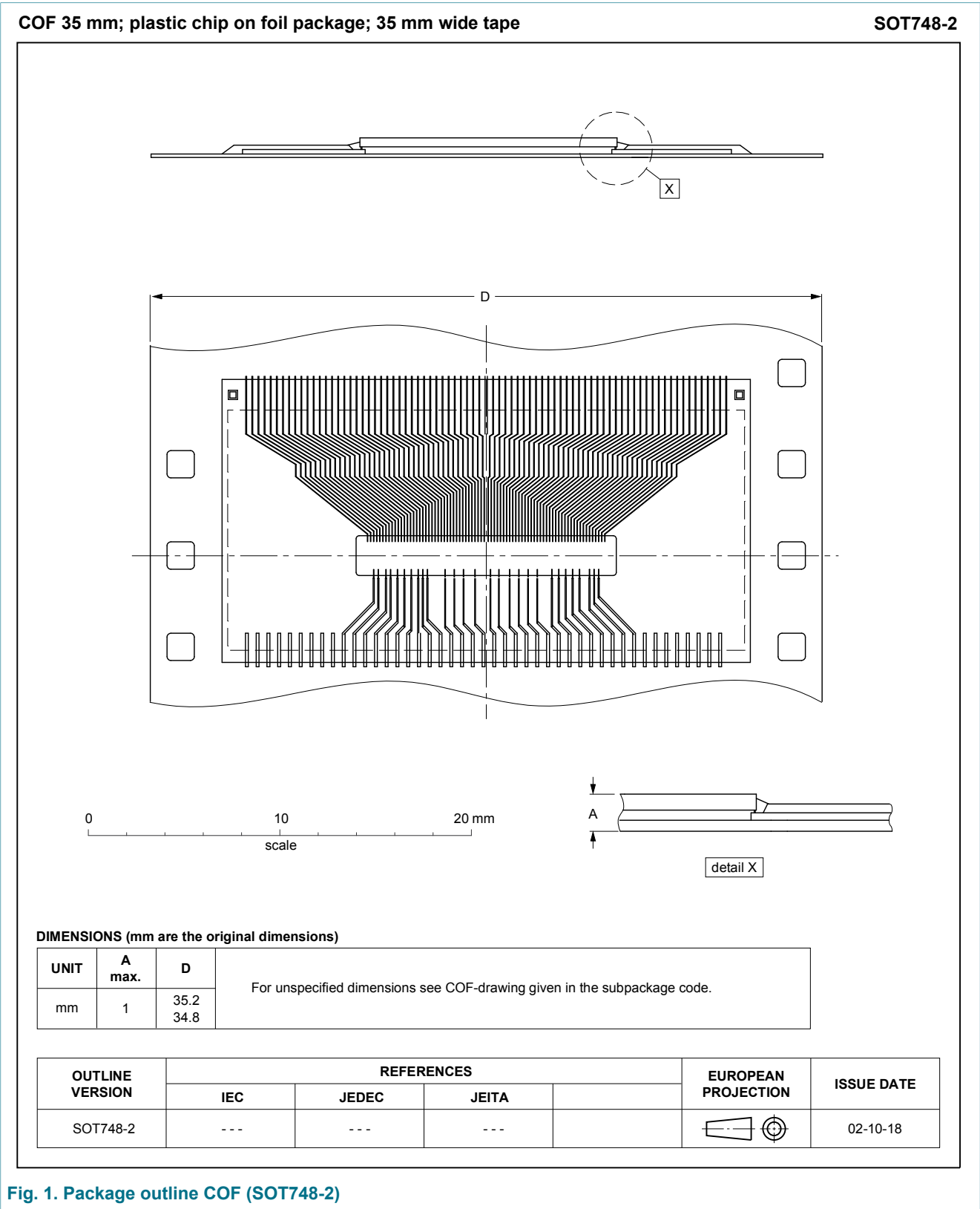


Fig. 1. Package outline COF (SOT748-2)

3. Legal information

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4. Contents

1. Package summary..... 1

2. Package outline..... 2

3. Legal information..... 3

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